

# MA27077

## Silicon epitaxial planar type

For band switching

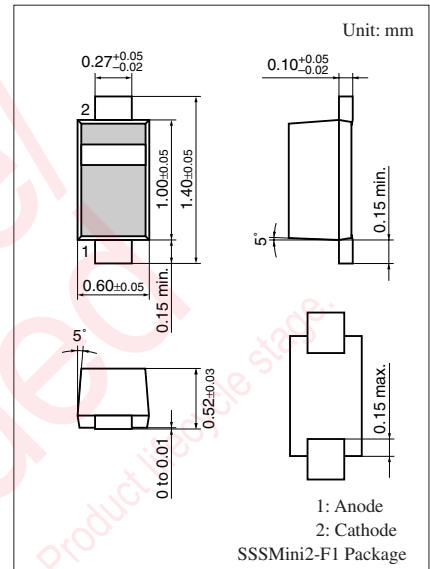
### ■ Features

- Low forward dynamic resistance  $r_f$
- Less voltage dependence of diode capacitance  $C_D$
- SSS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	35	V
Forward current	$I_F$	100	mA
Operating ambient temperature *	$T_{opr}$	-25 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

Note) \*: Maximum ambient temperature during operation.



Marking Symbol: C

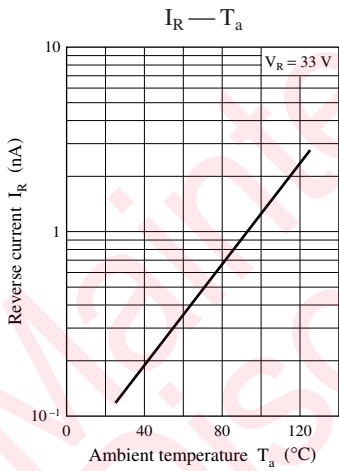
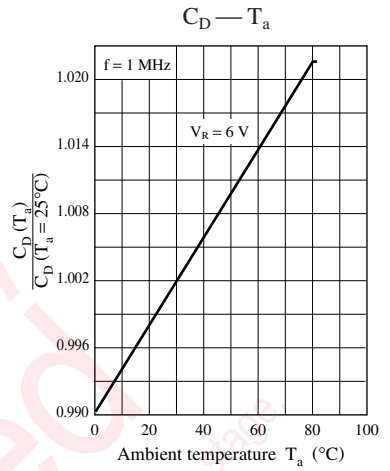
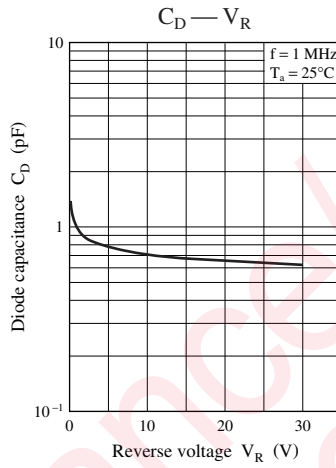
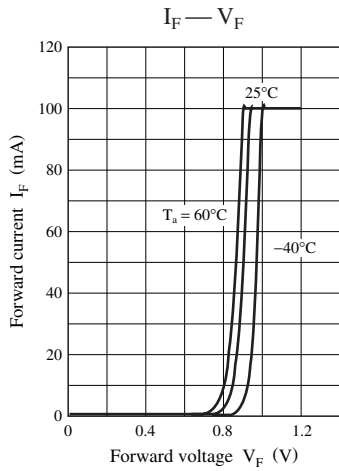
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 100 \text{ mA}$		0.92	1.00	V
Reverse current	$I_R$	$V_R = 33 \text{ V}$		0.01	100.00	nA
Diode capacitance	$C_D$	$V_R = 6 \text{ V}, f = 1 \text{ MHz}$		0.9	1.2	pF
Forward dynamic resistance *	$r_f$	$I_F = 2 \text{ mA}, f = 100 \text{ MHz}$		0.65	0.85	$\Omega$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

3. \*: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER



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